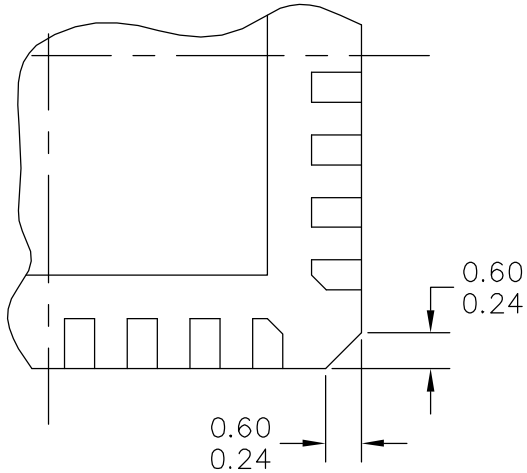
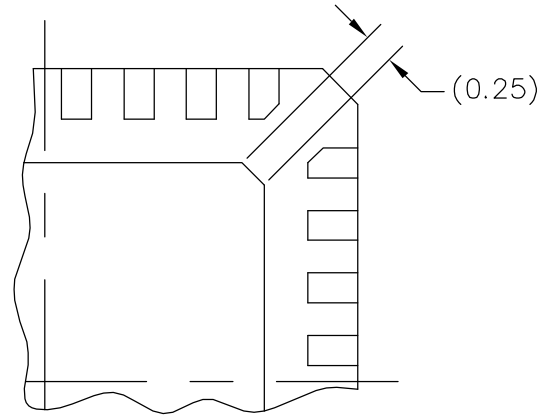


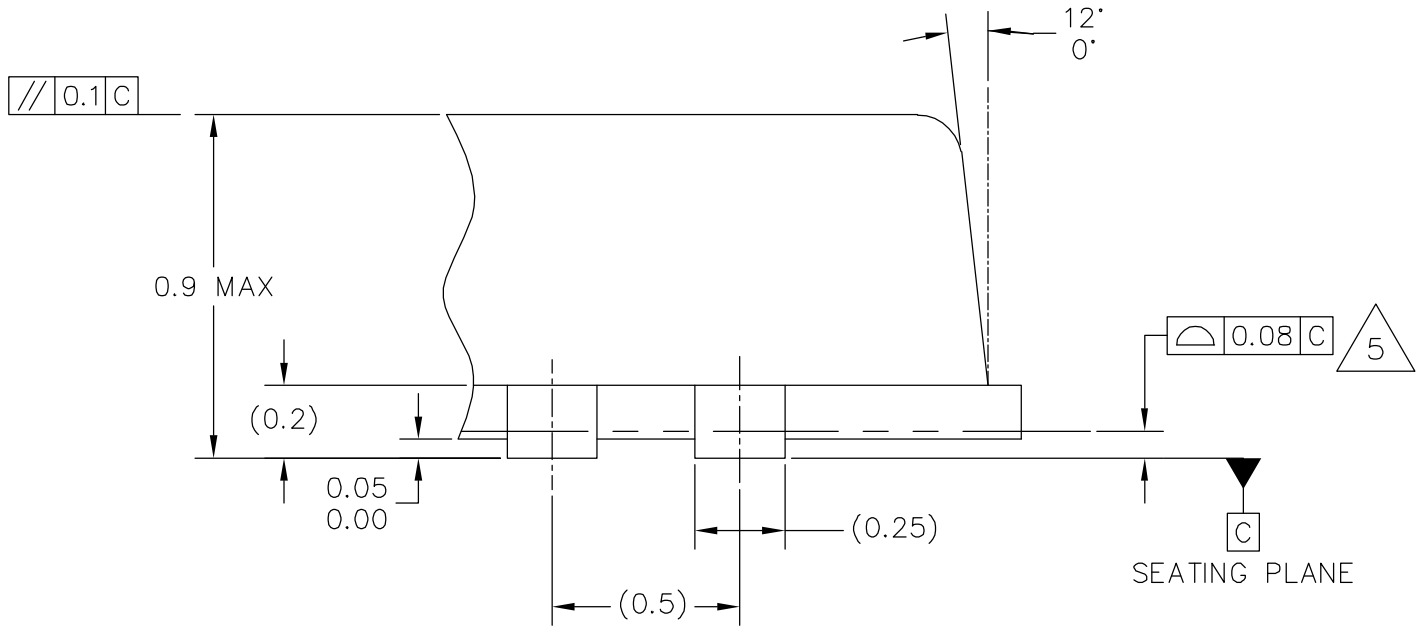
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1)	DOCUMENT NO: 98ARE10739D	REV: A
	STANDARD: JEDEC MO-220 VHHD-5	
	SOT617-15	02 FEB 2016



DETAIL N
CORNER CONFIGURATION OPTION



DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL G
VIEW ROTATED 90° CW

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		STANDARD: JEDEC MO-220 VHHD-5	
		SOT617-15	02 FEB 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
5. COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
6. MIN METAL GAP SHOULD BE 0.2MM.

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